

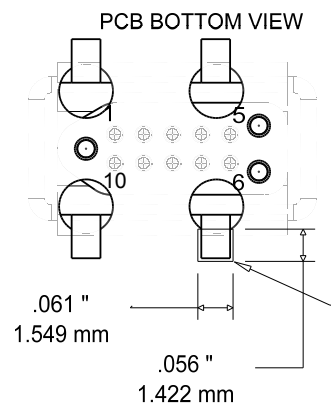
1. Allow clearance for finger squeeze access from the two sides shown.

- 3. No other track or signal within .02" of any contact pad.**

- 4. Do not allow solder paste on the contact pads. It is essential to eliminate any hole in the solder paste-mask (solder stencil) layer. If this is not possible make the contact pads thru-hole with a finished hole size of .008" or less.**

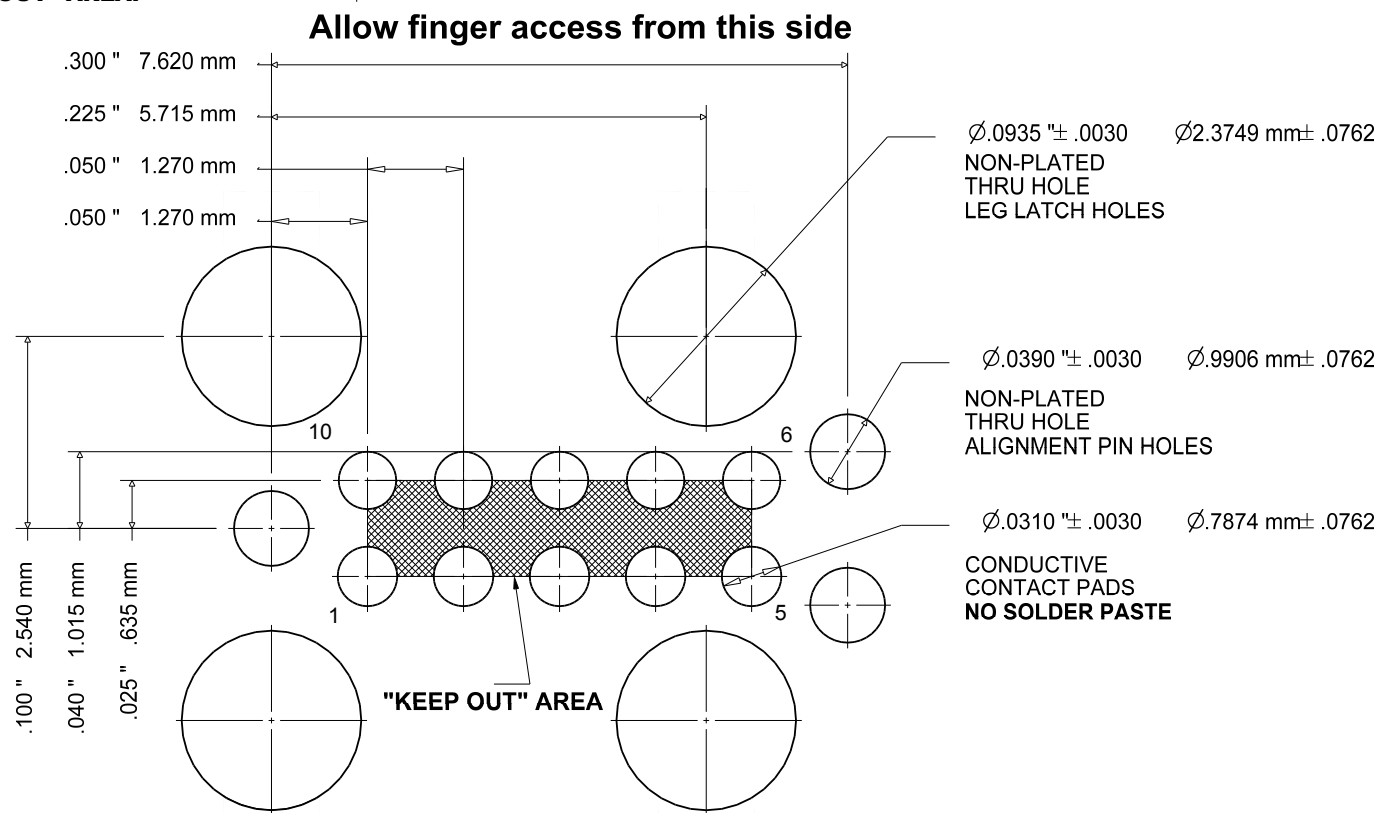
- 5. Leg and alignment holes may be plated and used as vias but ensure minimum finished hole size meets specified tolerances.**

- 6. To prevent purchasing confusion, please specify DNL in your BOM.**



ALLOW A .061 x .056
SQUARE AREA OF
CLEARANCE FOR
EACH FOOT

ZONE	A	TC2050-IDC-FP	12/2/10	MS
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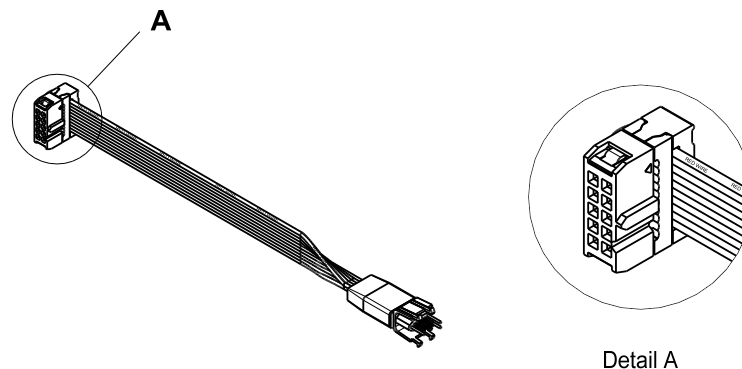
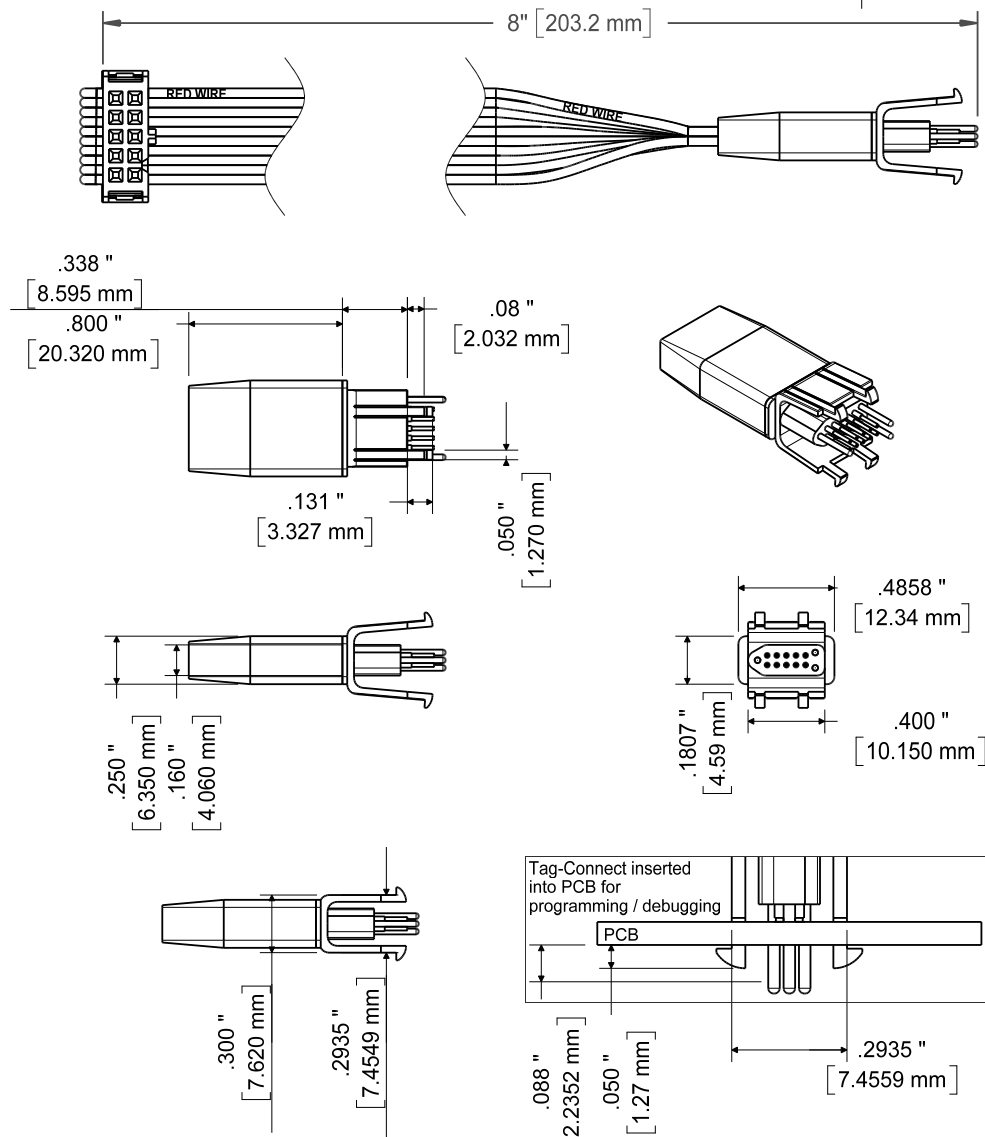
Allow finger access from this side

SIZE A	FSCM NO.	DWG NO.	FOOTPRINT FOR TC2050-IDC-FP	REV A
SCALE 7:1	www.TAG-CONNECT.com		SHEET 1 Of 3	

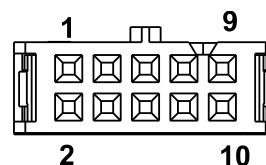
NOTE:
Dimensions subject to change

TC2050-IDC PLUG-OF-NAILS™ CABLE

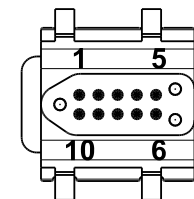
ZONE	A	TC2050-IDC	12/2/10	MS
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END VIEW
2x5 0.1" PITCH
IDC CONNECTOR

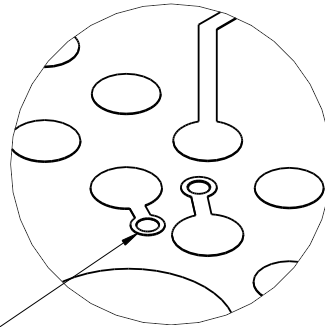
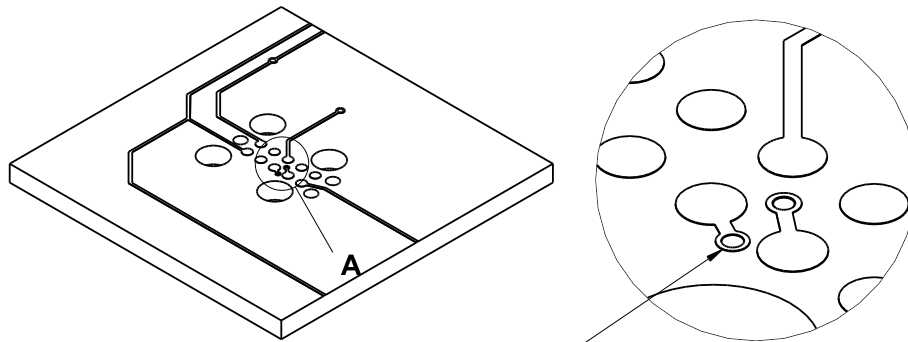


END VIEW
10 PIN
TAG-CONNECT



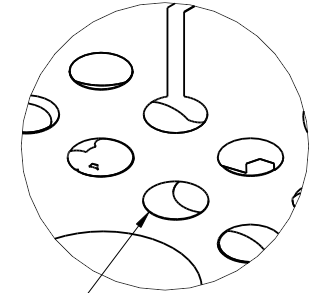
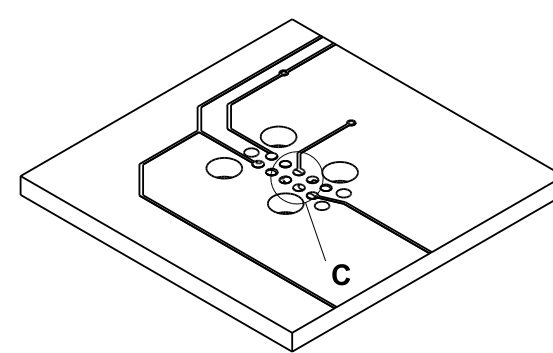
SIZE A	FSCM NO.	DWG NO. TC2050-IDC	REV A
SCALE	www.TAG-CONNECT.com		SHEET 2 Of 3

Layout Problems to Avoid



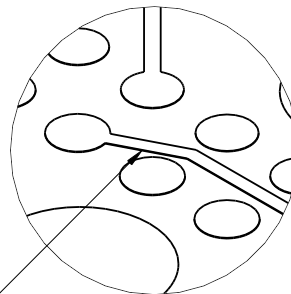
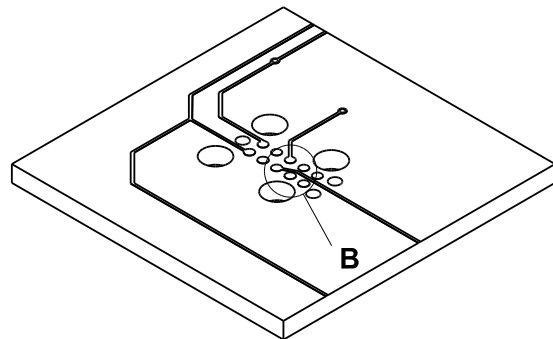
Detail A

Vias between
contact pads



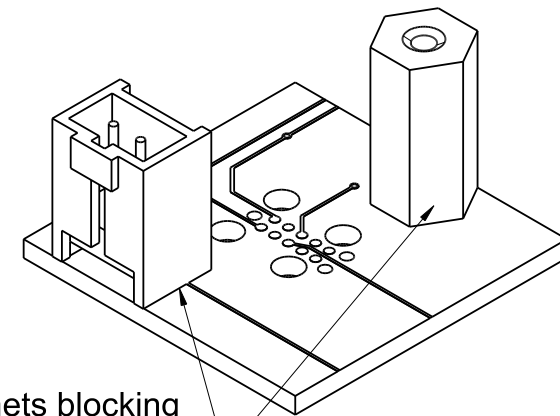
Detail C

Do not deposit solder paste on
contact pads. View Solder Paste
Mask (Solder Stencil) layer in
pad-stack and eliminate any hole.



Detail B

Traces less than .02"
away from contact pad
or in "KEEP OUT" area



Large componets blocking
finger access to the Tag-
Connect leg clips